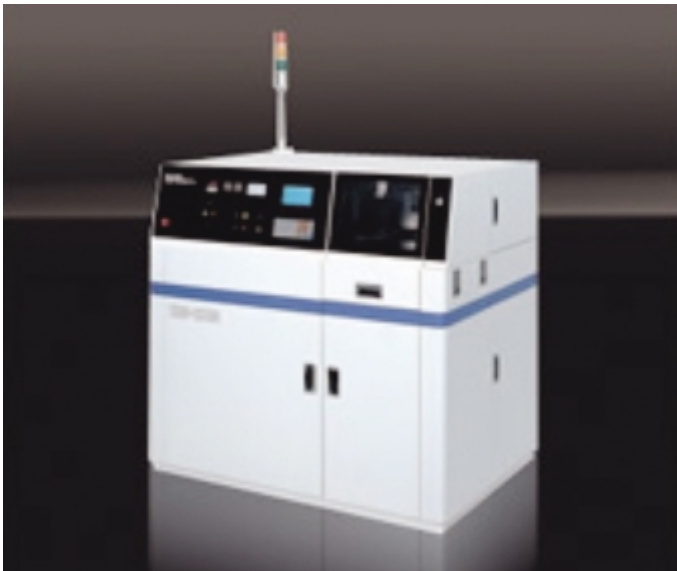


200mm Fully-Automatic UV Irradiation System

RAD-2000F/8



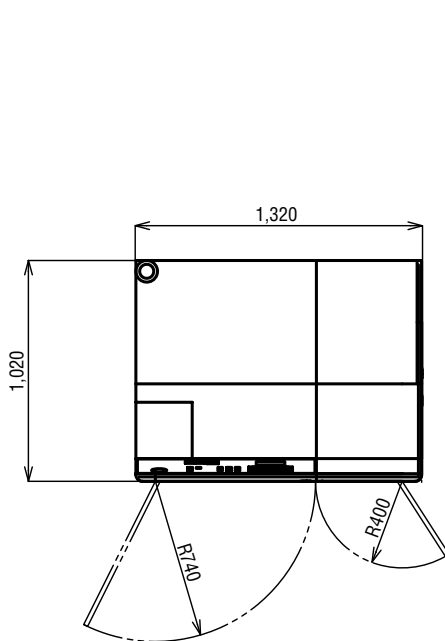
Outline

- Fully-automatic UV irradiation system used for curing UV type dicing tape.
- Applicable for ring frame sizes used for 150mm and 200mm wafers.

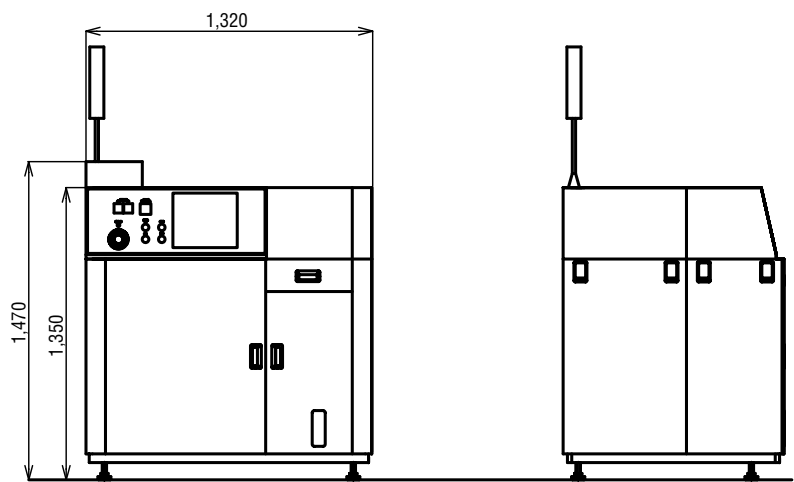
Option ·Host Communication Function (Communication Format :
Conforms to SECS-I and HSMS/Software : Conforms to GEM)

Suitable Tapes ·Dicing tape : Adwill D series
·Dicing die bonding tape : Adwill LE Tape

External View



Top View



Front View

Left Side View

Unit:mm

Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
Air Supply	Power consumption	: 5.0kW
	Air pressure	: 0.5-0.8MPa
	Air consumption	: >250L/min (ANR)
Nitrogen Source	Nitrogen pressure	: 0.29MPa
	Nitrogen consumption	: 30-50L/min (ANR)

Applicable Wafer Size 150mm, 200mm

Size
Width : 1,320mm
Depth : 1,020mm
Height : 1,470mm
(excluding the signal tower)

Weight 900kg

UPH 100wafers/hour

The above processing capacity is based on following conditions:

Wafer : 200mm diameter non-polished mirror wafer
Ring frame : for 200mm wafer



LINTEC Corporation *Linking your dreams*

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